

**AMENDMENTS TO THE CLAIMS:**

1. (Currently amended) A flexible wired circuit board for temperature measurement comprising;

a conductor layer ~~having a temperature detecting portion;~~ and

a base insulating layer formed entirely on said conductor layer;

wherein the conductor layer is formed from a metal foil having a proportional relation between temperature and specific electric resistance; and

wherein said conductor layer includes a temperature detecting portion formed when said conductor layer is formed as a wiring portion and arranged in a predetermined pattern on said base insulating layer.

2. (Currently amended) The flexible wired circuit board for temperature measurement according to ~~Claim~~ claim 1, wherein the conductor layer is a stainless foil.

3. (Currently amended) The flexible wired circuit board for temperature measurement according to ~~Claim~~ claim 1, wherein ~~the said wiring portion temperature detecting portion is formed in a pattern comprising~~ includes a wiring-folded in such a continuous form that adjacent parts of the wiring extending in parallel are spaced apart from each other at a predetermined interval.

4. (Currently amended) The flexible wired circuit board for temperature measurement according to ~~Claim~~ claim 3, wherein the wiring in the temperature detecting portion has an entire length of 50 mm or more.

5. (Currently amended) The flexible wired circuit board for temperature measurement according to ~~Claim~~ claim 3, wherein the adjacent parts of the wiring in the temperature detecting portion are spaced apart from each other at a pitch of 100  $\mu$  m or more.

6. (New) A method of preparing a flexible wired circuit board for temperature measurement, comprising:

providing a conductor layer formed from a metal foil and having a proportional relation between temperature and specific electric resistance;

forming a base insulating layer on said conductor layer; and

forming a temperature detecting portion on said base insulating layer, by forming a wiring from said conductor layer, said wiring being disposed in a predetermined pattern on said base insulating layer.

7. (New) The method according to claim 6, wherein said base insulating layer is formed by bonding a resin film to said conductor layer using an adhesive.

8. (New) The method according to claim 6, wherein said base insulating layer is formed by applying a resin solution to form a resin film, on said conductor layer.

9. (New) The method according to claim 6, further comprising:

forming said base insulating layer in a form of a predetermined shape.

10. (New) The method according to claim 6, wherein said conductor layer is formed in said predetermined pattern using a patterning process.

11. (New) The method according to claim 6, wherein said conductor layer is a stainless steel foil.

12. (New) The method according to claim 6, further comprising:  
forming a cover insulating layer on said base insulating layer and said conductor layer.

13. (New) The method according to claim 12, wherein said cover insulating layer is formed by applying a resin solution to form a film on said base insulating layer.

14. (New) The method according to claim 12, wherein said cover insulating layer is formed by bonding a resin film to said base insulating layer.

15. (New) The method according to claim 12, further comprising:  
forming openings for exposing a sensor wiring and connector wirings in said cover insulating layer.

16. (New) The method according to claim 12, wherein said cover insulating layer is formed in a predetermined pattern.

17. (New) The method according to claim 15, wherein a sensor portion is formed into a predetermined pattern by folding back said sensor wiring in a continuous form such that adjacent parts of said sensor wiring extending in parallel are spaced apart from each other at a predetermined interval in a widthwise direction.

18. (New) A flexible wired circuit board for temperature measurement comprising:  
a base insulating layer formed from a polyimide film; and  
a conductor layer formed from a stainless foil, and formed on said base insulating layer; and  
a cover insulating layer formed from a polyimide film, and formed on said conductor layer;  
wherein said conductor layer, comprising a main wiring portion for wiring and a sensor-wiring portion for detecting temperature, is formed in one piece in a form of a predetermined pattern.